**JETPRINTER MY700**

<https://www.mycronic.com/en/news/news-articles/a-game-changer-in-high-speed-jet-printing/>

**Multiple fluids.**

**Multiple ejectors.**

**Dual heads.**

**Higher speeds.**

In particular, its dual ejector heads, dual lanes and multiple ejector sizes have opened up opportunities to produce larger batches for a number of fast-growing customers.

<https://www.geminitec.co.uk/what-makes-us-unique/solder-jet-printing.html>

With over 80% of typical SMT production errors directly attributed to the use of stencils, solder jet printing delivers the technical solution for high yield and high reliability manufacturing for today's most complex SMT products.

The very latest model has twin heads to provide faster processing times by using two dispensing heads simultaneously, together with smaller dot capability for sub 0.25mm pad sizes.

**How does solder jet paste printing work?**

Jet printing is a non-contact printing process that applies solder paste directly onto the PCB pad, without the need to use any stencil tooling.

Small solder paste deposits are placed at a rate of over 1 million dots per hour, to accurately construct the optimum solder paste typography for each and every pad position on the board. Such close control allows us to obtain the optimum reflow conditions first time and every time.

Jet printing removes the limitations of traditional stencils, to deliver a new level of reliability for rigid and flexible substrates, board cavities, package-on-package, QFNs and new components with small process windows. By optimising the solder paste process we are able to remove the typical production errors, such as floating QFN devices, excessive and insufficient solder, that lead to poor production yields, higher build costs and the inevitable time delays.

Assured delivery times can be achieved without the constraints of using stencils. We are able to adopt a lean, fast and cost-effective approach to SMT/PCB production, regardless of lead-time and complexity.

* 100% accurate repeatable, without deviation.
* Optimum solder joints, typical yields at 100%.
* No stencil tooling costs.
* Process development in real time.
* Lower manufacturing costs.
* Shorter lead times and no risk of production delays.
* Suitable for all SMT devices, BGA, PoP, QFN devices.\*\*\*\*
* Optimised for 3D cavity printing and technical components
* The only UK CEM operating with three solder jet paste printers

\*BGA =Bilyalı ızgara dizisi, entegre devreler için kullanılan bir yüzeye monte ambalaj türüdür.

\*PoP = Package on Package

 delivering higher levels of product quality beyond the capability of stencils.

**JETPRINTER MY600**

<https://www.mycronic.com/globalassets/brochures/p-001-0281-my600-platform-brochure-may-2016.pdf>

Highly accurate,

On-the-fly solder paste jet printing,

Allowing manufacturers to achieve optimal solder joints of any shape and size – on demand.

The MY600 Jet Printer allows you to produce complex boards with unmatched precision at a speed of more than one million dots per hour.

It handles flexible substrates, board cavities and packageon package applications with ease.

High-precision,

Having non-contact nozzle ensures perfect solder paste deposits to reduce re-work and increase overall throughput.

Çip montajı sırasında doğru kontrol ve hassas yerleştirme çok önemlidir bu yüzden de dispense sistemin hızı çok kritiktir.

SMD montajı sırasında dispense sisteminin hızlı, hassas ve küçük kalıplar için kullanıma uygun olması gerekmektedir. Çünkü SMD lerde küçük ve büyük kalıpların yanyana işlenmesini gerektirdiğinden dolayı bu işlem zordur.

**Özellikleri;**

1. **Design freedom (Tasarım özgürlüğü)**

Ideal for shielding, flexible substrates, cavities, package-on-package and mixed technology boards.

1. **Superior quality**

Perfect volume control for each individual solder joint, independent of operator.

Operatörden bağımsız mükemmel kontrol sistemi

1. **100% software driven**

Prepare a new job offline in minutes from any CAD or Gerber data. Allow product changes down to batch size one.

1. **Fast NPIs**

Paste volume adjustments in minutes instead of days.

Kullanılacak paste volume ü hızlıca ayarlanabilir.

1. **No stencils**

Eliminate stencil storage, cleaning and handling and stop waiting for stencil deliveries.

Şablon processlerinden kurtulma

1. **Repeatability**

Automatic board stretch and board warpage compensation.

The MY600 Jet Printer makes it possible to handle the most challenging boards and components with micrometer accuracy, maximum speed and perfect quality solder joints.

For many manufacturers, the drawbacks of screen printing are becoming increasingly clear. In fact, a significant majority of all PCB defects can be traced back to the screen printing process. And for every quality challenge solved with traditional needle dispensers comes a new bottleneck in line utilization. With solder paste jet printing, these compromises are a thing of the past.

Jet printing ile screen printingdeki dezavantajlardan kurtulabliliriz.

As boards and components become smaller, smarter and more complex, jet printing stands out as the most efficient solution for the modern electronics industry.

Fully software-driven and with complete solder paste volume control, the MY600 is the optimal way to ensure perfect quality solder joints at high speed – even in the industry’s most challenging applications.

Kartlar ve bileşenler küçüldükçe, daha akıllı ve daha karmaşık hale geldikçe, jet baskı modern elektronik endüstrisi için en verimli çözüm olarak öne çıkıyor. Tamamen yazılım odaklı ve eksiksiz lehim pastası hacim kontrolü ile MY600, endüstrinin en zorlu uygulamalarında bile yüksek hızda mükemmel kalitede lehim bağlantıları sağlamanın en uygun yoludur.

MY600 platform is an advanced self-learning data preparation system – one that stores your process knowledge to improve speed and quality with every job to boost performance.

In addition to almost completely eliminating the risk for human errors, the MY600’s closed-loop, software-driven system allows your entire data set to be easily integrated with the rest of your production environment to ensure the absolute highest level of factorywide automation.

**Mycronic My600 User’s Manual**

Quick offline programming

Reduced lead times (processin başlama ve bitme süresi arasındaki zaman)

Increased product quality

Increased profitability

**Functions;**

Cad data importing to process into the assembly data

Rapid and offline machine program generation

Panelization

**Benefits**

Elimination of manual data as needed ones (Bom(bill of materials) and coordinate data)

Fast bom to cad comparison

Fast setup for new projects

Gainig time from the manual machine teaching

The time that is gained from the teaching and offline programming is used to build more boards

Engineering changes are fast

Central management of part number databases